

Block Analyzing System

LBA 300 3D



Brick with ductile
polish ground surface
from G&N MPS 134



Automatic cropping line marker

Features

The LBA 300 3D is designed and built specifically to inspect multi-crystalline silicon bricks for PV wafer production

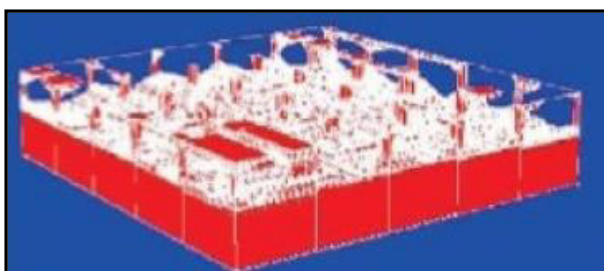
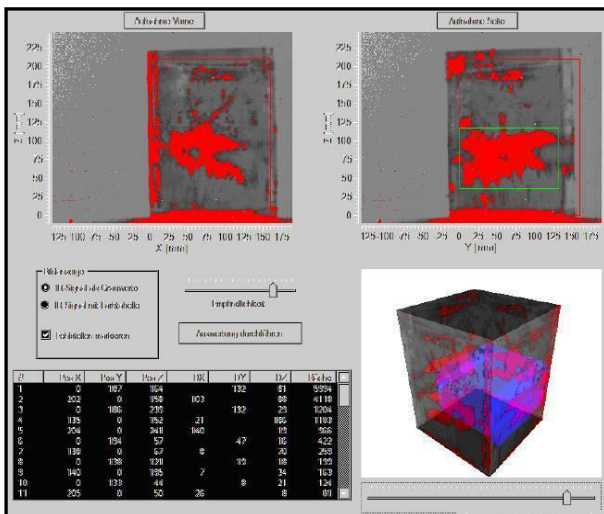
- Reliable detection of harmful
 - SiC nests
 - microcrystals
 - cracks
- Reduction of wire breakage in wafer saw
- Help to increase wafer yield
- Quick circle time
- Loading manually or by inline system
- 3D brick model – reconstruction of ingot crystallization process

Capacity

- Loading capacity: one brick
- Brick size:
 - 125 mm x 125 mm
 - 156 mm x 156 mm
 - 210 mm x 210 mm max.
- Brick height: max. 300 mm
- Cycle time: approx. 1 min / brick (incl. loading&unloading)
500 bricks / day

Technical data

Dimension	1.65 m x 0.8 m x 1.9 m
Weight	180 kg (including crop line marker option)
Control	PLC for machine operation, PC with GUI for inspection
El. Connection	max. 2 kW 230 V, 13~, ground wire 50 Hz
Color	white



Our LBA 300 3D system gives our customers the possibility to put the 24 scanned bricks (156 x 156) together to see how the ingot was crystallized and to inform the ingot supplier for quality properties.